

Rui Huang

List of Publications by Year in descending order

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166
papers

11,404
citations

28190

55
h-index

30010

103
g-index

167
all docs

167
docs citations

167
times ranked

10905
citing authors

#	ARTICLE	IF	CITATIONS
1	Two-Dimensional Phonon Transport in Supported Graphene. <i>Science</i> , 2010, 328, 213-216.	6.0	1,692
2	A review on mechanics and mechanical properties of 2D materials—Graphene and beyond. <i>Extreme Mechanics Letters</i> , 2017, 13, 42-77.	2.0	920
3	Elastic Moduli of Ultrathin Amorphous Polymer Films. <i>Macromolecules</i> , 2006, 39, 5095-5099.	2.2	389
4	Elastic bending modulus of monolayer graphene. <i>Journal Physics D: Applied Physics</i> , 2009, 42, 102002.	1.3	326
5	Kinetic wrinkling of an elastic film on a viscoelastic substrate. <i>Journal of the Mechanics and Physics of Solids</i> , 2005, 53, 63-89.	2.3	280
6	Dielectric elastomer actuators under equal-biaxial forces, uniaxial forces, and uniaxial constraint of stiff fibers. <i>Soft Matter</i> , 2012, 8, 6167.	1.2	237
7	Interfacial Sliding and Buckling of Monolayer Graphene on a Stretchable Substrate. <i>Advanced Functional Materials</i> , 2014, 24, 396-402.	7.8	229
8	Impact of Near-Surface Thermal Stresses on Interfacial Reliability of Through-Silicon Vias for 3-D Interconnects. <i>IEEE Transactions on Device and Materials Reliability</i> , 2011, 11, 35-43.	1.5	228
9	Wrinkling of a compressed elastic film on a viscous layer. <i>Journal of Applied Physics</i> , 2002, 91, 1135-1142.	1.1	223
10	NONLINEAR MECHANICS OF SINGLE-ATOMIC-LAYER GRAPHENE SHEETS. <i>International Journal of Applied Mechanics</i> , 2009, 01, 443-467.	1.3	222
11	Inhomogeneous deformation in metallic glasses. <i>Journal of the Mechanics and Physics of Solids</i> , 2002, 50, 1011-1027.	2.3	220
12	Buckling modes of elastic thin films on elastic substrates. <i>Applied Physics Letters</i> , 2007, 90, 151902.	1.5	179
13	Internal lattice relaxation of single-layer graphene under in-plane deformation. <i>Journal of the Mechanics and Physics of Solids</i> , 2008, 56, 1609-1623.	2.3	164
14	Concomitant wrinkling and buckle-delamination of elastic thin films on compliant substrates. <i>Mechanics of Materials</i> , 2011, 43, 627-642.	1.7	159
15	Thermo-mechanical reliability of 3-D ICs containing through silicon vias. , 2009, , .		158
16	Measuring Interlayer Shear Stress in Bilayer Graphene. <i>Physical Review Letters</i> , 2017, 119, 036101.	2.9	155
17	Swelling kinetics of polymer gels: comparison of linear and nonlinear theories. <i>Soft Matter</i> , 2012, 8, 8194.	1.2	146
18	Modeling quasi-static crack growth with the extended finite element method Part II: Numerical applications. <i>International Journal of Solids and Structures</i> , 2003, 40, 7539-7552.	1.3	143

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19	Bending of Multilayer van der Waals Materials. <i>Physical Review Letters</i> , 2019, 123, 116101.	2.9	139
20	Thermomechanics of monolayer graphene: Rippling, thermal expansion and elasticity. <i>Journal of the Mechanics and Physics of Solids</i> , 2014, 66, 42-58.	2.3	138
21	Effects of mismatch strain and substrate surface corrugation on morphology of supported monolayer graphene. <i>Journal of Applied Physics</i> , 2010, 107, .	1.1	136
22	Mechanics of spontaneously formed nanoblisters trapped by transferred 2D crystals. <i>Proceedings of the National Academy of Sciences of the United States of America</i> , 2018, 115, 7884-7889.	3.3	130
23	Atomistic simulation and continuum modeling of graphene nanoribbons under uniaxial tension. <i>Modelling and Simulation in Materials Science and Engineering</i> , 2011, 19, 054006.	0.8	121
24	Stretch-induced stress patterns and wrinkles in hyperelastic thin sheets. <i>International Journal of Solids and Structures</i> , 2011, 48, 3471-3483.	1.3	109
25	Interfacial adhesion between graphene and silicon dioxide by density functional theory with van der Waals corrections. <i>Journal Physics D: Applied Physics</i> , 2014, 47, 255301.	1.3	109
26	Instability of a compressed elastic film on a viscous layer. <i>International Journal of Solids and Structures</i> , 2002, 39, 1791-1802.	1.3	108
27	Channel-cracking of thin films with the extended finite element method. <i>Engineering Fracture Mechanics</i> , 2003, 70, 2513-2526.	2.0	108
28	Effect of Thermal Stresses on Carrier Mobility and Keep-Out Zone Around Through-Silicon Vias for 3-D Integration. <i>IEEE Transactions on Device and Materials Reliability</i> , 2012, 12, 255-262.	1.5	106
29	Selective Mechanical Transfer of Graphene from Seed Copper Foil Using Rate Effects. <i>ACS Nano</i> , 2015, 9, 1325-1335.	7.3	104
30	A nonlinear, transient finite element method for coupled solvent diffusion and large deformation of hydrogels. <i>Journal of the Mechanics and Physics of Solids</i> , 2015, 79, 21-43.	2.3	102
31	Swell-induced surface instability of confined hydrogel layers on substrates. <i>Journal of the Mechanics and Physics of Solids</i> , 2010, 58, 1582-1598.	2.3	100
32	Effect of surface roughness on adhesion of graphene membranes. <i>Journal Physics D: Applied Physics</i> , 2011, 44, 452001.	1.3	100
33	Analytical methods for the mechanics of graphene bubbles. <i>Journal of Applied Physics</i> , 2012, 112, .	1.1	99
34	Dynamics of wrinkle growth and coarsening in stressed thin films. <i>Physical Review E</i> , 2006, 74, 026214.	0.8	98
35	Characterization of thermal stresses in through-silicon vias for three-dimensional interconnects by bending beam technique. <i>Applied Physics Letters</i> , 2012, 100, 041901.	1.5	96
36	Measurement and analysis of thermal stresses in 3D integrated structures containing through-silicon-vias. <i>Microelectronics Reliability</i> , 2013, 53, 53-62.	0.9	96

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37	Micro-Raman spectroscopy and analysis of near-surface stresses in silicon around through-silicon vias for three-dimensional interconnects. <i>Journal of Applied Physics</i> , 2012, 111, .	1.1	94
38	Anisotropic, Hierarchical Surface Patterns via Surface Wrinkling of Nanopatterned Polymer Films. <i>Nano Letters</i> , 2012, 12, 5995-5999.	4.5	88
39	A blister test for interfacial adhesion of large-scale transferred graphene. <i>Carbon</i> , 2014, 69, 390-400.	5.4	88
40	A Variational Approach and Finite Element Implementation for Swelling of Polymeric Hydrogels Under Geometric Constraints. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2010, 77, .	1.1	86
41	Thermal stress induced delamination of through silicon vias in 3-D interconnects. , 2010, , .		85
42	Excess energy and deformation along free edges of graphene nanoribbons. <i>Physical Review B</i> , 2010, 81, .	1.1	78
43	Ultra Long-Range Interactions between Large Area Graphene and Silicon. <i>ACS Nano</i> , 2014, 8, 11234-11242.	7.3	75
44	Wrinkle patterns of anisotropic crystal films on viscoelastic substrates. <i>Journal of the Mechanics and Physics of Solids</i> , 2008, 56, 3315-3330.	2.3	73
45	Swell-induced surface instability of hydrogel layers with material properties varying in thickness direction. <i>International Journal of Solids and Structures</i> , 2013, 50, 578-587.	1.3	73
46	Strain relaxation of SiGe islands on compliant oxide. <i>Journal of Applied Physics</i> , 2002, 91, 9716.	1.1	70
47	Isothermal stress relaxation in electroplated Cu films. I. Mass transport measurements. <i>Journal of Applied Physics</i> , 2005, 97, 103531.	1.1	70
48	Electromechanical phase transition in dielectric elastomers. <i>Proceedings of the Royal Society A: Mathematical, Physical and Engineering Sciences</i> , 2012, 468, 1014-1040.	1.0	69
49	Evolving crack patterns in thin films with the extended finite element method. <i>International Journal of Solids and Structures</i> , 2003, 40, 2343-2354.	1.3	64
50	Nonlinear analysis of compressed elastic thin films on elastic substrates: From wrinkling to buckle-delamination. <i>International Journal of Solids and Structures</i> , 2014, 51, 3715-3726.	1.3	64
51	Effect of Surface Properties on Wrinkling of Ultrathin Films. <i>Journal of Aerospace Engineering</i> , 2007, 20, 38-44.	0.8	63
52	Unique Aspects of a Shape Memory Polymer As the Substrate for Surface Wrinkling. <i>ACS Applied Materials & Interfaces</i> , 2012, 4, 598-603.	4.0	62
53	Nonlinear effect of stress and wetting on surface evolution of epitaxial thin films. <i>Physical Review B</i> , 2006, 74, .	1.1	61
54	Viscoelastic properties of confined polymer films measured via thermal wrinkling. <i>Soft Matter</i> , 2009, 5, 4638.	1.2	61

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55	Mechanics at the interfaces of 2D materials: Challenges and opportunities. <i>Current Opinion in Solid State and Materials Science</i> , 2020, 24, 100837.	5.6	61
56	Numerical Analysis of Circular Graphene Bubbles. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2013, 80, .	1.1	60
57	Pathâ€Guided Wrinkling of Nanoscale Metal Films. <i>Advanced Materials</i> , 2012, 24, 3010-3014.	11.1	57
58	Plasticity mechanism for copper extrusion in through-silicon vias for three-dimensional interconnects. <i>Applied Physics Letters</i> , 2013, 103, .	1.5	57
59	Effect of Solvent Diffusion on Crack-Tip Fields and Driving Force for Fracture of Hydrogels. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2015, 82, .	1.1	55
60	Cracking of Polycrystalline Graphene on Copper under Tension. <i>ACS Nano</i> , 2016, 10, 9616-9625.	7.3	53
61	Nanostructured block copolymer muscles. <i>Nature Nanotechnology</i> , 2022, 17, 752-758.	15.6	53
62	Influence of interfacial delamination on channel cracking of elastic thin films. <i>International Journal of Fracture</i> , 2007, 148, 331-342.	1.1	52
63	Stretch-induced wrinkling of polyethylene thin sheets: Experiments and modeling. <i>International Journal of Solids and Structures</i> , 2014, 51, 1847-1858.	1.3	52
64	A comparison of direct and iterative methods for determining traction-separation relations. <i>International Journal of Fracture</i> , 2012, 177, 109-128.	1.1	50
65	Through-silicon via stress characteristics and reliability impact on 3D integrated circuits. <i>MRS Bulletin</i> , 2015, 40, 248-256.	1.7	50
66	Swelling behavior of nanoscale, shape- and size-specific, hydrogel particles fabricated using imprint lithography. <i>Soft Matter</i> , 2011, 7, 2879.	1.2	49
67	Thermal fluctuations and effective bending stiffness of elastic thin sheets and graphene: A nonlinear analysis. <i>Journal of the Mechanics and Physics of Solids</i> , 2017, 107, 294-319.	2.3	49
68	Creases and wrinkles on the surface of a swollen gel. <i>Journal of Applied Physics</i> , 2013, 114, .	1.1	46
69	Effect of passivation on stress relaxation in electroplated copper films. <i>Journal of Materials Research</i> , 2006, 21, 1512-1518.	1.2	44
70	On determining mixed-mode tractionâ€separation relations for interfaces. <i>International Journal of Fracture</i> , 2016, 202, 1-19.	1.1	44
71	Loss of constraint on fracture in thin film structures due to creep. <i>Acta Materialia</i> , 2002, 50, 4137-4148.	3.8	42
72	Relaxation of compressed elastic islands on a viscous layer. <i>Acta Materialia</i> , 2002, 50, 2933-2944.	3.8	41

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73	Show of adhesive strength. <i>Nature Nanotechnology</i> , 2011, 6, 537-538.	15.6	41
74	Mixed-mode traction-separation relations between graphene and copper by blister tests. <i>International Journal of Solids and Structures</i> , 2016, 84, 147-159.	1.3	39
75	Effect of surface tension on swell-induced surface instability of substrate-confined hydrogel layers. <i>Soft Matter</i> , 2010, 6, 5736.	1.2	38
76	Electromechanical coupling in piezoelectric nanobeams due to the flexoelectric effect. <i>Smart Materials and Structures</i> , 2017, 26, 095025.	1.8	37
77	Isothermal stress relaxation in electroplated Cu films. II. Kinetic modeling. <i>Journal of Applied Physics</i> , 2005, 97, 103532.	1.1	33
78	Buckling suppression of SiGe islands on compliant substrates. <i>Journal of Applied Physics</i> , 2003, 94, 6875-6882.	1.1	32
79	SWELLING-INDUCED INSTABILITY OF SUBSTRATE-ATTACHED HYDROGEL LINES. <i>International Journal of Applied Mechanics</i> , 2011, 03, 219-233.	1.3	32
80	A multiscale cohesive zone model for rate-dependent fracture of interfaces. <i>Journal of the Mechanics and Physics of Solids</i> , 2020, 145, 104142.	2.3	30
81	Steady-state crack growth in polymer gels: A linear poroelastic analysis. <i>Journal of the Mechanics and Physics of Solids</i> , 2018, 118, 15-39.	2.3	29
82	Fabrication and Characterization of Patterned Single-Crystal Silicon Nanolines. <i>Nano Letters</i> , 2008, 8, 92-98.	4.5	28
83	Very thin solid-on-liquid structures: the interplay of flexural rigidity, membrane force, and interfacial force. <i>Thin Solid Films</i> , 2003, 429, 273-281.	0.8	27
84	Salt-Induced Swelling and Volume Phase Transition of Polyelectrolyte Gels. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2017, 84, .	1.1	27
85	Extensional, thickness-stretch and symmetric thickness-shear vibrations of piezoceramic disks. <i>IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control</i> , 2002, 49, 1507-1515.	1.7	25
86	Mixed-Mode Interactions Between Graphene and Substrates by Blister Tests. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2015, 82, .	1.1	25
87	Characterizing Interfacial Sliding of Through-Silicon-Via by Nano-Indentation. <i>IEEE Transactions on Device and Materials Reliability</i> , 2017, 17, 355-363.	1.5	25
88	Thermomechanical Failure Analysis of Through-Silicon Via Interface Using a Shear-Lag Model With Cohesive Zone. <i>IEEE Transactions on Device and Materials Reliability</i> , 2014, 14, 318-326.	1.5	23
89	Rate-dependent traction-separation relations for a silicon/epoxy interface informed by experiments and bond rupture kinetics. <i>Journal of the Mechanics and Physics of Solids</i> , 2019, 131, 1-19.	2.3	23
90	Simultaneous extraction of tensile and shear interactions at interfaces. <i>Journal of the Mechanics and Physics of Solids</i> , 2019, 125, 225-254.	2.3	22

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91	Vibrations and static responses of asymmetric bimorph disks of piezoelectric ceramics. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2000, 47, 706-715.	1.7	21
92	A State Space Method for Surface Instability of Elastic Layers With Material Properties Varying in Thickness Direction. Journal of Applied Mechanics, Transactions ASME, 2014, 81, .	1.1	21
93	Effects of a liquid layer on thickness-shear vibrations of rectangular AT-cut quartz plates. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2002, 49, 604-611.	1.7	20
94	Thermomechanical reliability of through-silicon vias in 3D interconnects. , 2011, , .		20
95	Wrinkling and folding of thin films by viscous stress. Soft Matter, 2015, 11, 1814-1827.	1.2	19
96	Entropic effects of thermal rippling on van der Waals interactions between monolayer graphene and a rigid substrate. Journal of Applied Physics, 2016, 119, .	1.1	18
97	Peeling and sliding of graphene nanoribbons with periodic van der Waals interactions. Journal of the Mechanics and Physics of Solids, 2022, 158, 104698.	2.3	18
98	Onset of swell-induced surface instability of hydrogel layers with depth-wise graded material properties. Mechanics of Materials, 2017, 105, 138-147.	1.7	17
99	Mechanical effects of electrodes on the vibrations of quartz crystal plates. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2002, 49, 612-625.	1.7	16
100	Thermal Stresses Analysis of 3-D Interconnect. , 2009, , .		16
101	Wet adhesion of graphene. Extreme Mechanics Letters, 2015, 3, 130-140.	2.0	16
102	Study of Stresses and Plasticity in Through-Silicon Via Structures for 3D Interconnects by X-Ray Micro-Beam Diffraction. IEEE Transactions on Device and Materials Reliability, 2014, 14, 698-703.	1.5	15
103	Stress-Induced Delamination Of Through Silicon Via Structures. AIP Conference Proceedings, 2011, , .	0.3	14
104	Effect of elastic anisotropy on surface pattern evolution of epitaxial thin films. International Journal of Solids and Structures, 2009, 46, 2822-2833.	1.3	13
105	Initiation and propagation of interfacial delamination in integrated thin-film structures. , 2010, , .		13
106	Snap Transitions of Pressurized Graphene Blisters. Journal of Applied Mechanics, Transactions ASME, 2016, 83, .	1.1	13
107	Rate-Dependent Decohesion Modes in Graphene-Sandwiched Interfaces. Advanced Materials Interfaces, 2019, 6, 1901217.	1.9	13
108	Electrically induced surface instability of a conductive thin film on a dielectric substrate. Applied Physics Letters, 2005, 87, 151911.	1.5	12

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109	A Linear Poroelastic Analysis of Time-Dependent Crack-Tip Fields in Polymer Gels. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2018, 85, .	1.1	12
110	Rate dependent fracture along a silicon/epoxy interface under mixed-mode loading conditions. <i>International Journal of Solids and Structures</i> , 2022, 257, 111129.	1.3	12
111	Poroelastic Effects on the Time- and Rate-Dependent Fracture of Polymer Gels. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2020, 87, .	1.1	12
112	A fast simulation framework for full-chip thermo-mechanical stress and reliability analysis of through-silicon-via based 3D ICs. , 2011, , .		11
113	Cavitation of water by volume-controlled stretching. <i>Extreme Mechanics Letters</i> , 2017, 11, 59-67.	2.0	11
114	Torsional vibrations of circular elastic plates with thickness steps. <i>IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control</i> , 2006, 53, 349-359.	1.7	10
115	Thermomechanical Reliability Challenges For 3D Interconnects With Through-Silicon Vias. <i>AIP Conference Proceedings</i> , 2010, , .	0.3	10
116	Temperature-dependent thermal stress determination for through-silicon-vias (TSVs) by combining bending beam technique with finite element analysis. , 2011, , .		10
117	Phonon interaction with ripples and defects in thin layered molybdenum disulfide. <i>Applied Physics Letters</i> , 2019, 114, .	1.5	10
118	Analytical Electromechanical Modeling of Nanoscale Flexoelectric Energy Harvesting. <i>Applied Sciences (Switzerland)</i> , 2019, 9, 2273.	1.3	10
119	Mechanics of relaxing SiGe islands on a viscous glass. <i>Acta Mechanica Sinica/Lixue Xuebao</i> , 2002, 18, 441-456.	1.5	9
120	Impact of Process Induced Stresses and Chip-Packaging Interaction on Reliability of Air-gap Interconnects. , 2008, , .		9
121	Bifurcation of surface pattern in epitaxial thin films under anisotropic stresses. <i>Journal of Applied Physics</i> , 2007, 101, 023519.	1.1	8
122	Bending with slip. <i>Nature Materials</i> , 2020, 19, 259-260.	13.3	8
123	Poroelastic effects on steady state crack growth in polymer gels under plane stress. <i>Mechanics of Materials</i> , 2020, 143, 103320.	1.7	8
124	Linear and nonlinear poroelastic analysis of swelling and drying behavior of gelatin-based hydrogels. <i>International Journal of Solids and Structures</i> , 2020, 195, 43-56.	1.3	8
125	Impact of Grain Structure and Material Properties on Via Extrusion in 3D Interconnects. <i>Journal of Microelectronics and Electronic Packaging</i> , 2015, 12, 118-122.	0.8	8
126	Processing Effect on Via Extrusion for TSVs in Three-Dimensional Interconnects: A Comparative Study. <i>IEEE Transactions on Device and Materials Reliability</i> , 2016, 16, 465-469.	1.5	7

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127	Rate-dependent wrinkling and subsequent bifurcations of an elastic thin film on a viscoelastic layer. International Journal of Solids and Structures, 2022, 257, 111592.	1.3	7
128	Effect of a cap layer on morphological stability of a strained epitaxial film. Journal of Applied Physics, 2005, 97, 113537.	1.1	6
129	Trapped torsional vibrations in elastic plates. Applied Physics Letters, 2005, 87, 201911.	1.5	6
130	Effects of Passivation Layer on Stress Relaxation and Mass Transport in Electroplated Cu Films. AIP Conference Proceedings, 2004, , .	0.3	5
131	Characterization of plasticity and stresses in TSV structures in stacked dies using synchrotron x-ray microdiffraction. , 2013, , .		5
132	Impact of material and microstructure on thermal stresses and reliability of through-silicon via (TSV) structures. , 2013, , .		5
133	Material characterization and failure analysis of through-silicon vias. , 2014, , .		5
134	Energy-Trapping Torsional-Mode Resonators for Liquid Sensing. , 2006, , .		4
135	Wrinkling of Ultrathin Polymer Films. Materials Research Society Symposia Proceedings, 2006, 924, 1.	0.1	4
136	Characterization of thermal stresses and plasticity in through-silicon via structures for three-dimensional integration. AIP Conference Proceedings, 2014, , .	0.3	4
137	Effect of high temperature storage on the stress and reliability of 3D stacked chip. , 2014, , .		4
138	Finite element modeling of stress variation in multilayer thin-film specimens for in situ transmission electron microscopy experiments. Journal of Materials Research, 2007, 22, 2737-2741.	1.2	3
139	Buckling of Single-Crystal Silicon Nanolines under Indentation. Journal of Nanomaterials, 2008, 2008, 1-11.	1.5	3
140	Interfacial Delamination Between Through Silicon Vias (TSVs) and Silicon Matrix. , 2010, , .		3
141	Measurement and analysis of thermal stresses in 3-D integrated structures containing through-silicon vias. , 2012, , .		3
142	Effect of microstructure on via extrusion profile and reliability implication for copper through-silicon vias (TSVs) structures. , 2014, , .		3
143	A kinetic decomposition process for air-gap interconnects and induced deformation instability of a low-k dielectric cap layer. Journal of Mechanical Science and Technology, 2014, 28, 255-261.	0.7	3
144	Thermal stress characteristics and impact on device keep-out zone for 3-D ICs containing through-silicon vias. , 2012, , .		2

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145	Thermomechanical characterization and modeling for TSV structures. , 2014, , .		2
146	Effect of Cu grain boundary sliding on TSV extrusion. , 2015, , .		2
147	The effect of moisture on the nonlinearly viscoelastic behavior of an epoxy. Mechanics of Time-Dependent Materials, 2020, 24, 435-461.	2.3	2
148	A Kinetics Approach to Surface Wrinkling of Elastic Thin Films. , 2013, , 69-109.		2
149	Influence of Interfacial Delamination on Channel Cracking of Brittle Thin Films. Materials Research Society Symposia Proceedings, 2007, 990, 1.	0.1	1
150	Fracture, delamination, and buckling of elastic thin films on compliant substrates. Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, 2008, , .	0.0	1
151	Indentation of single-crystal silicon nanolines: Buckling and contact friction at nanoscales. Journal of Applied Physics, 2009, 105, 073510.	1.1	1
152	Nanoindentation of Si Nanostructures: Buckling and Friction at Nanoscales. , 2009, , .		1
153	“Mechanical Behavior of Nanostructured Materials” Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2010, 41, 777-777.	1.1	1
154	Disparate tendency of stress evolution of thin and thick electroplated Cu films at room temperature. , 2010, , .		1
155	Nonlinear Mechanical Properties of Graphene Nanoribbons. Materials Research Society Symposia Proceedings, 2011, 1284, 165.	0.1	1
156	Thermal stress characteristics and reliability impact on 3-D ICs containing through-silicon-vias. , 2012, , .		1
157	Investigation of thermo-mechanical stresses and reliability of 3D die-stack structures by synchrotron x-ray micro-diffraction. , 2015, , .		1
158	Morphological Instability of Solid-on-Liquid Thin Film Structures. Materials Research Society Symposia Proceedings, 2002, 749, 1.	0.1	0
159	Trapped Torsional Vibrations in Elastic Plates. , 2006, , .		0
160	Pattern Evolution of Self-Assembled Quantum Dots Under Biaxial Stresses. Materials Research Society Symposia Proceedings, 2006, 921, 1.	0.1	0
161	Mechanical Characterization of High Aspect Ratio Silicon Nanolines. Materials Research Society Symposia Proceedings, 2008, 1086, 1.	0.1	0
162	Thermal Stress in 3-D Packaging. , 2014, , 5208-5217.		0

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163	Impact of Grain Structure and Material Properties on Via Extrusion in 3-D Interconnects. International Symposium on Microelectronics, 2014, 2014, 000008-000012.	0.3	0
164	Direct and Simultaneous Extraction of Mixed-Mode Traction-Separation Relations. Conference Proceedings of the Society for Experimental Mechanics, 2018, , 79-84.	0.3	0
165	Characterizing Traction-Separation Relations of TSV/SI Interfaces by Nanoindentation. Conference Proceedings of the Society for Experimental Mechanics, 2018, , 41-46.	0.3	0
166	Analytical and finite element study on warpage and stress of 2.5D chip-package structures. , 2021, , .		0